

EO1016

July 2010

PRODUCT DESCRIPTION

EO1016 provides the following product characteristics:

Technology	Ероху		
Appearance (cured)	Black		
Product Benefits	Excellent shelf stability		
	Fast curing		
	flame-out		
Components	One-component		
Cure	Heat cure		
Application	Encapsulant		
Typical Applications	IC's, transistors and similar semiconductors		
Flammability	Passes UL 94V-0		

EO1016 is an epoxy encapsulant intended for applications requiring excellent handling properties. The cured material survives severe thermal shock and offers continuous service to 177 °C. It is particularly suited for use on transistors and similar semiconductors, can be used for encapsulation of watch ICs.

TYPICAL PROPERTIES OF UNCURED MATERIAL

Viscosity, Brookfield - RVF, 25 °C, mPa·s (cP):	
Spindle 6, speed 2	62,000
Spindle 6, speed 20	58,000
Thixotropic Index	1.1
Specific Gravity @ 25°C	1.56
Shelf Life:	
@ 4°C, months	12
@ -40°C, months	12
Gel Time @ 121°C, minutes	4.5
Pot life @ 25 °C, months	3
Flash Point - See MSDS	

TYPICAL CURING PERFORMANCE Recommended Cure Schedule

20 minutes @ 150°C

Alternative Cure Schedule

24 hours @ 93°C

The above cure profile is a guideline recommendation. Cure conditions (time and temperature) may vary based on customers' experience and their application requirements, as well as customer curing equipment, oven loading and actual oven temperatures.

Differential Scanning Calorimetry

Initial Temperature, °C	122
Peak Temperature, °C	138
Energy to break point, Joules	0.414

TYPICAL PROPERTIES OF CURED MATERIAL

Physical Properties:

,		
Coefficient of Linear Thermal Expansion, ppm/°C:		
Below Tg	46	
Above Tg	140	

	Glass Transition Temperature, °C		126	
	Coefficient of Thermal Conductivity, W/(m·K)		0.39	
	Extractable Ionic Content, , ppm:		4.0	
	Chloride (CI-)		1.2	
	Tensile Strength	N/mm²		
		(psi)	(8,000)	
	Flexural Modulus	N/mm²	5,880	
		(psi)	(852,600)	
	Flexural strength	N/mm²	100	
		(psi)	(14,500)	
	Adhesion psi		3,660	
	Cohesive			
	Al-Al Tensile shear			
	Elongation, %		1.8	
	Shore Hardness , Durometer D		≥86	
	Linear Shrinkage, 10 grams, %		1.7	
	Moisture Absorption, %:			
	24 hours immersion @ 25°C		0.06	
	24 hours immersion @ 50°C		0.23	

Electrical Properties:

Dielectric Constant / Dissipation Factor, IEC 60250: @ 25 °C:		
Arc Resistance, AS	TM D495,	180
Volume Resistivity,	IEC 60093,	6×10 ¹⁵
Surface Resistivity,	IEC 60093,	1×10 ¹⁶

GENERAL INFORMATION

For safe handling information on this product, consult the Material Safety Data Sheet, (MSDS).

Not for product specifications

The technical data contained herein are intended as reference only. Please contact your local quality department for assistance and recommendations on specifications for this product.

Directions for use

- 1. Mix thoroughly each time it is used.
- 2. Heating to 32 to 43°C will lower viscosity and aid in mixing and pouring.



Storage

Store product in the unopened container in a dry location. Storage information may be indicated on the product container labeling.

Liquid Storage - Liquids should be stored at 23°C or below, in closed containers. If stored below 23°C, the material MUST be allowed to come to room temperature, in the sealed container, to avoid moisture contamination.

Material removed from containers may be contaminated during use. Do not return product to the original container. Henkel Corporation cannot assume responsibility for product which has been contaminated or stored under conditions other than those previously indicated. If additional information is required, please contact your local Technical Service Center or Customer Service Representative.

Conversions

(°C x 1.8) + 32 = °F kV/mm x 25.4 = V/mil mm / 25.4 = inches N x 0.225 = lb N/mm x 5.71 = lb/in N/mm² x 145 = psi MPa x 145 = psi N·m x 8.851 = lb·in N·m x 0.738 = lb·ft N·mm x 0.142 = oz·in mPa·s = cP

Note

The data contained herein are furnished for information only and are believed to be reliable. We cannot assume responsibility for the results obtained by others over whose methods we have no control. It is the user's responsibility to determine suitability for the user's purpose of any production methods mentioned herein and to adopt such precautions as may be advisable for the protection of property and of persons against any hazards that may be involved in the handling and use thereof. In light of the foregoing, Henkel Corporation specifically disclaims all warranties expressed or implied, including warranties of merchantability or fitness for a particular purpose, arising from sale or use of Henkel Corporation's products. Henkel Corporation specifically disclaims any liability for consequential or incidental damages of any kind, including lost profits. The discussion herein of various processes or compositions is not to be interpreted as representation that they are free from domination of patents owned by others or as a license under any Henkel Corporation patents that may cover such processes or compositions. We recommend that each prospective user test his proposed application before repetitive use, using this data as a guide. This product may be covered by one or more United States or foreign patents or patent applications.

Trademark usage

Except as otherwise noted, all trademarks in this document are trademarks of Henkel Corporation in the U.S. and elsewhere. [®] denotes a trademark registered in the U.S. Patent and Trademark Office.

Reference 0.0